

Amendment under 37 C.F. R. § 1.111  
Application No. 10/009,822

**AMENDMENTS TO THE SPECIFICATION**

**Please replace the present title with the following amended title:**

~~MATERIAL FOR A HEAT DISSIPATION SUBSTRATE FOR MOUNTING A  
SEMICONDUCTOR, METHOD OF PRODUCING THE SAME, AND CERAMIC PACKAGE  
USING THE SAME METHOD OF PRODUCING A HEAT DISSIPATION SUBSTRATE OF  
MOLYBDENUM POWDER IMPREGNATED WITH COPPER WITH ROLLING IN  
PRIMARY AND SECONDARY DIRECTIONS~~